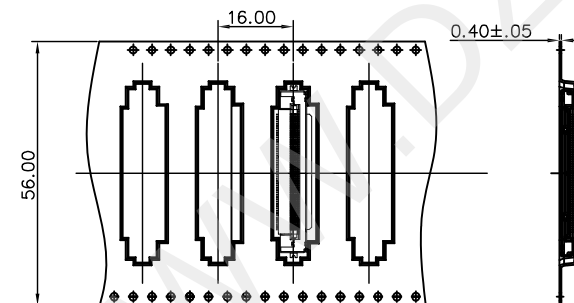
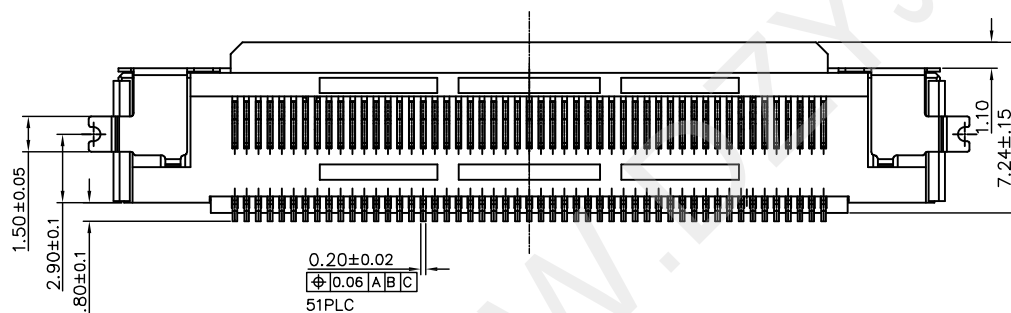
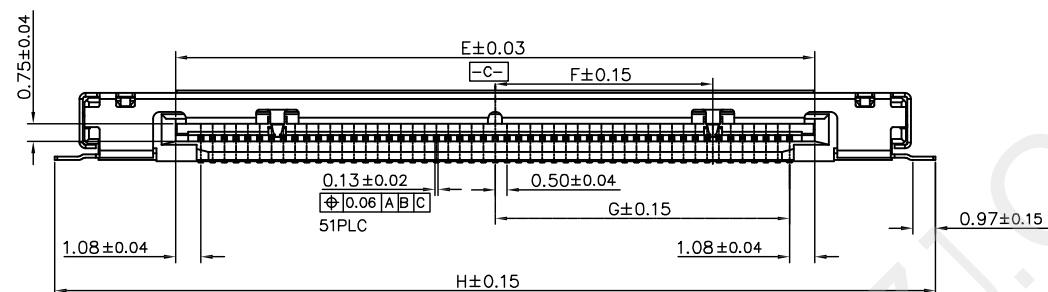
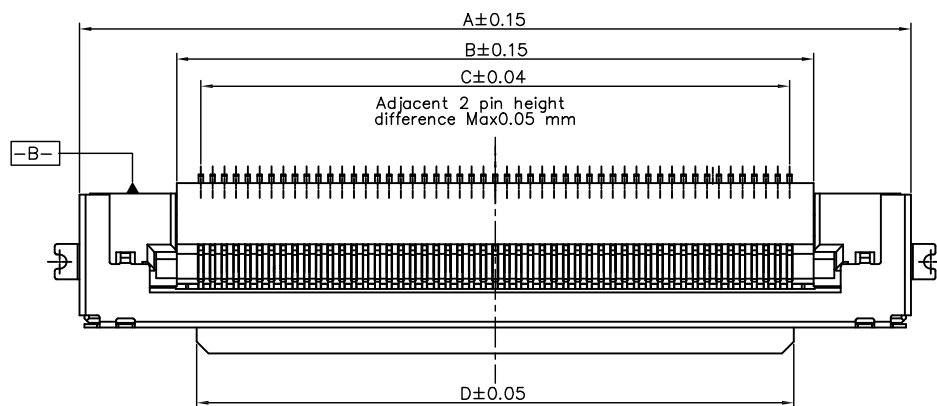
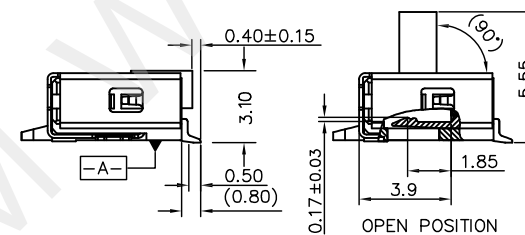




EMBOSS PACKING



OPEN POSITION

NOTES:

1. MATERIAL:

HOUSING: HEIGHT TERMOPLASTIC, UL94V_0, COLOR: NATURE
SLIDER HEIGHT TERMOPLASTIC, PPA UL94V_0, COLOR: BLACK
CONTACT: COPPER ALLOY, T=0.20mm
SHELL: STAINLESS STEEL, T=0.15mm

2. FINISH:

CONTACT: 3u" Min GOLD PLATING ON CONTACT AREA
MATTE TIN 75u" Min SOLDER AREA. 50u" NICKEL BASE-PLATE
SHELL: 75u" Min MATTE TIN OVERALL 50u" Min NICKEL
UNDER PLATED. (LEAD FREE)

3. SPECIFICATIONS:

VOLTAGE RATING: 50VAC rms.
CURRENT RATING: 0.5A Max./CONTACT.
INSULATION RESISTANCE: 100MEG.OHM MIN
CONTACT RESISTANCE: 40 MILL.OHM MAX
OPERATION TEMPERATURE: -40°C TO +85°C
DURABILITY: 20 CYCLES.

FFC/FPC RETENTION FORCE: 0.6N MIN/PIN

4. COPLANARITY BETWEEN TERMINAL AND HOLD DOWN OF SHELL
SHOULD BE 0.08mm MAX.

DIM	H	37.40
	G	12.50
	F	9.25
	E	27.15
	D	25.35
	C	25.00
	B	27.05
	A	35.30
PIN		51P

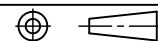


深圳市华宇创精密电子有限公司

TOLERANCE:

X.X ±0.30
X.XX ±0.25
X.XXX ±0.15

X' ±2" X.X' ±0.5"



UNIT: mm [inch]

SCALE: 1:1 SIZE: A4

DRAWN BY :

陈一鸣

DATE :

2014-02-23

PART NAME:

0.5PH 3.1H 前插后压FPC

CHECKED BY:

马跃

DATE :

2014-02-23

PART NO.

HYCD-05FPCXX-310

APPROVED BY:

邱敏

DATE :

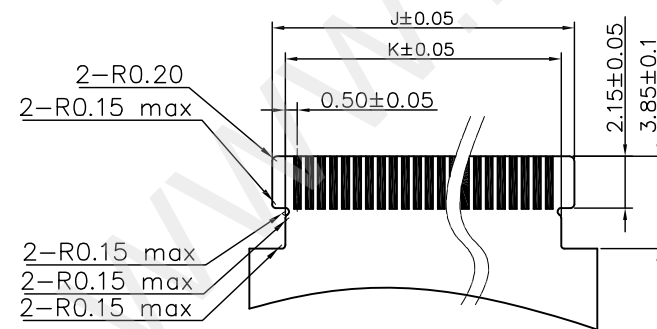
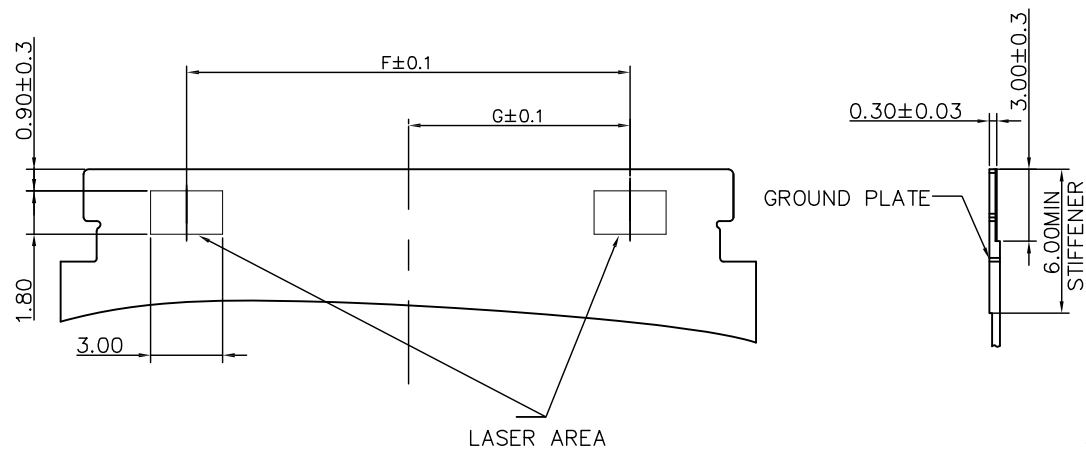
2014-02-23

DRAW NO:

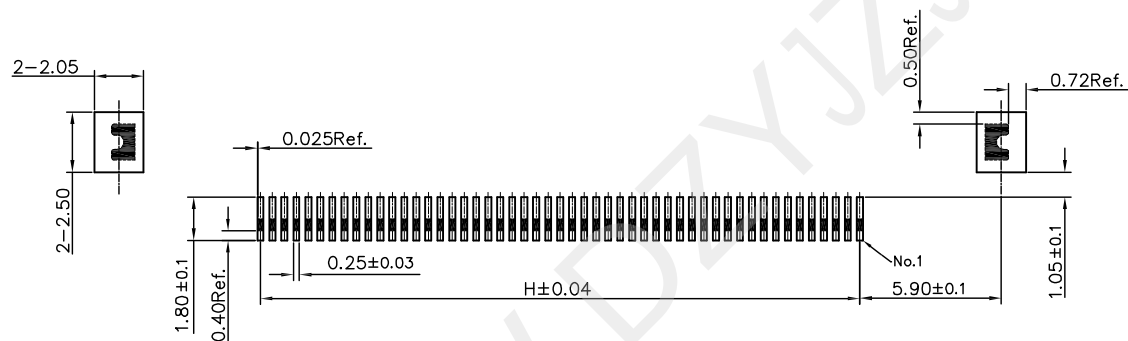
HYC-2303061020

SHEET NO.

1 OF 1



RECOMMENDED FPC DIMENSIONS



RECOMMENDED PCB LAYOUT

DIM	K	26.00
	J	27.10
	G	9.25
	F	18.50
PIN		51P



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2" X.X' ±0.5"	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: 0.5PH 3.1H 前插后压FPC
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYCD-05FPCXX-310
 UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO: HYC-2303061020
			SHEET NO. 1 OF 1